



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Charles W.C. Lin

Title: BUMBLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA

Serial No.: 09/852,824 Filed: May 10, 2001

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ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

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G. J. G.  
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102800 MAIL ROOM  
APR 23 2002

**THIRD PRELIMINARY AMENDMENT**

Dear Sir:

Please amend the application as follows.

**In the Claims**

Add the following claims:

1        95.     The method as recited in claim 15, wherein the reflowable material  
2     extends continuously between the first and second surfaces in the via hole after the  
3     reflowing.

1        96.     The method as recited in claim 15, wherein the reflowable material is the  
2     only material in the via hole that contacts the metallization after the reflowing.

1        97.     The method as recited in claim 15, wherein the reflowable material is the  
2     only material in the via hole that contacts the pad after the reflowing.

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